



#6A
1/2/03
Arrr

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Ching-Fa YEH et al.

Serial No: 10/075,293

Filed: February 15, 2002

Group Art Unit: 2814

Examiner: H. Trinh

For: METHOD OF REDUCING THICK FILM STRESS OF SPIN-ON DIELECTRIC
AND THE RESULTING SANDWICH DIELECTRIC STRUCTURE

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DEC 31 2002
TECHNOLOGY CENTER 2800

AMENDMENT

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

This is in response to the Official Action of December 3, 2002, in connection with the above-identified application.

Please amend the above-identified application as follows.

IN THE CLAIMS:

Please cancel claims 1-24 from the application without prejudice or disclaimer.